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(12) United States Design Patent

Heng et al.

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(54) **CIRCUIT PACKAGE LID**

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(**) Term: **14 Years**

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Related U.S. Application Data

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182; 439/70, 71, 72, 73, 74, 330, 331, 620.2
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D288,803	S	3/1987	Capawana
D295,401	S	4/1988	Klees
4,918,513	A	4/1990	Kurose et al.
D313,686	S	1/1991	Vitek
5,486,771	A	1/1996	Volz et al.
D379,350	S	5/1997	Kerklaan
D407,382	S	3/1999	Acciaioli et al.
6,746,253	B1	6/2004	Ma
6,805,562	B2	10/2004	Liao et al.
7,014,488	B2	3/2006	Stone
7,291,022	B2	11/2007	Toda et al.
7,367,815	B2	5/2008	Ma
7,374,446	B2	5/2008	Toda et al.
7,396,248	B2	7/2008	Zhang
7,435,103	B2	10/2008	Ma
7,497,743	B2	3/2009	Tsai
7,527,503	B1	5/2009	Polnyi
7,666,020	B2	2/2010	Zhang et al.
7,708,579	B2	5/2010	Yeh
7,753,703	B2	7/2010	Liao et al.

(Continued)

OTHER PUBLICATIONS

Picture of Socket F design; from www.commons.wikimedia.org; Mar. 25, 2010.

(Continued)

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(57) **CLAIM**

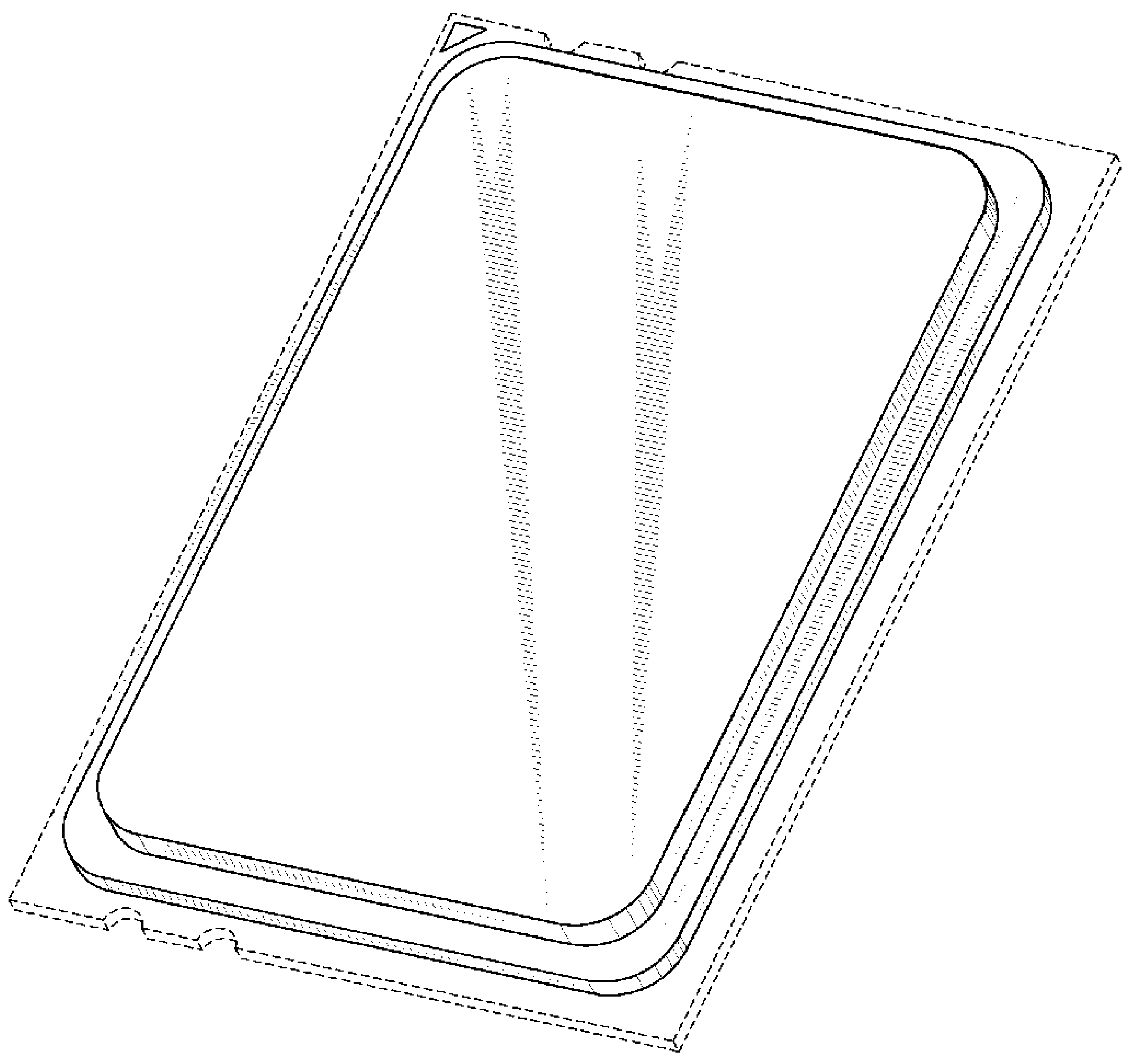
The ornamental design for a circuit package lid, as shown and described.

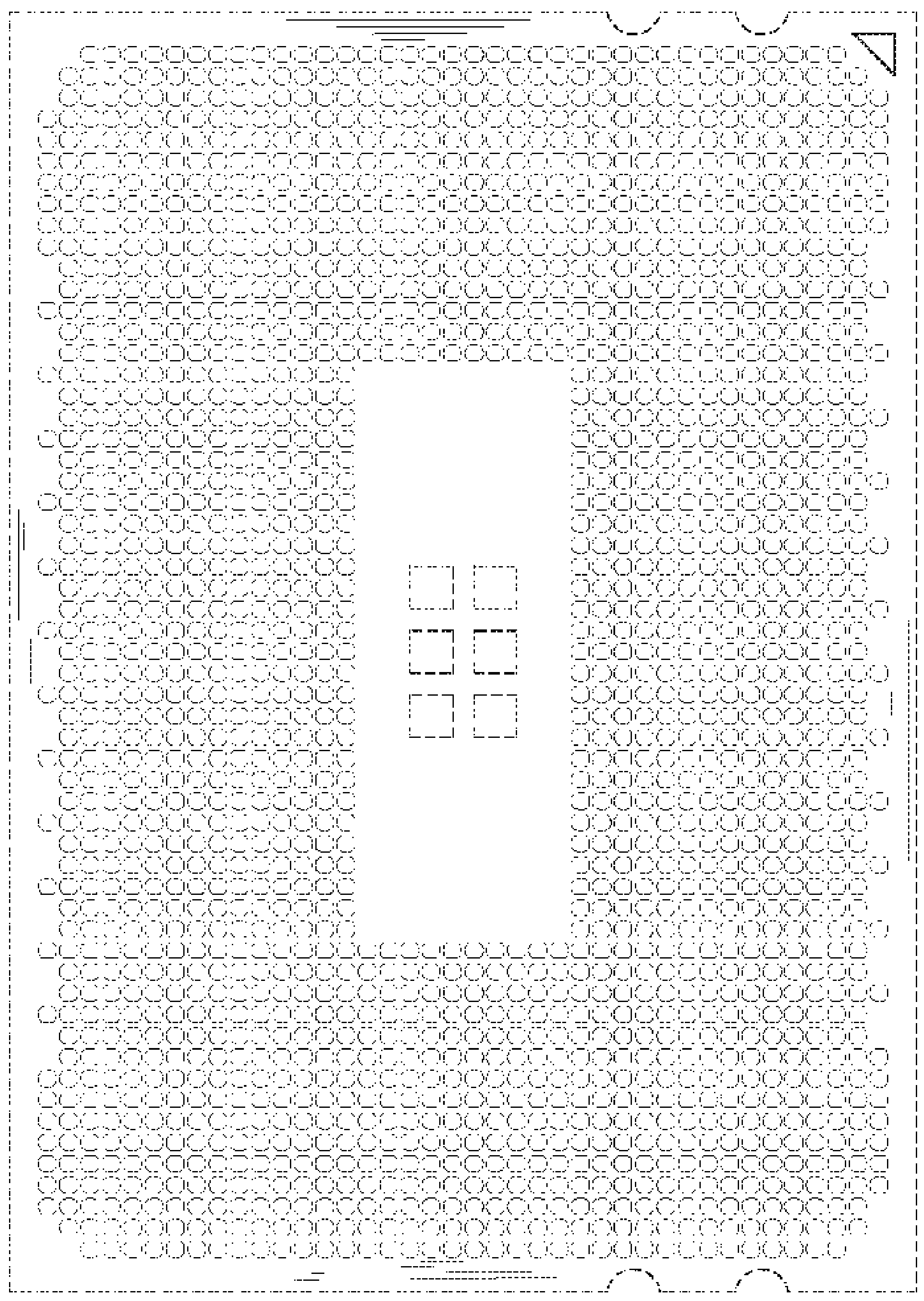
DESCRIPTION

FIG. **1** is a front perspective view of the circuit package lid;
FIG. **2** is a front view of the circuit package lid;
FIG. **3** is a top view of the circuit package lid;
FIG. **4** is a bottom view of the circuit package lid;
FIG. **5** is a left side view of the circuit package lid;
FIG. **6** is a right side view of the circuit package lid; and,
FIG. **7** is a rear view of the circuit package lid.

The broken line showing of the circuit package lid is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 3 Drawing Sheets





U.S. PATENT DOCUMENTS

7,798,856	B2		9/2010	Liao	
D633,877	S		3/2011	Heng et al.	
D633,878	S		3/2011	Heng et al.	
D633,879	S		3/2011	Heng et al.	
D633,880	S		3/2011	Heng et al.	
D641,720	S	*	7/2011	Heng et al.	D13/182
2005/0233629	A1		10/2005	Tsai	
2005/0287837	A1		12/2005	Trobough	
2006/0199413	A1		9/2006	Ju	
2007/0173081	A1		7/2007	Yu et al.	
2008/0242138	A1		10/2008	Chang	
2010/0062623	A1		3/2010	Chen et al.	

OTHER PUBLICATIONS

Advanced Micro Devices; AMD Socket F (1207) Design Specification; Publication No. 31700; Revision 1.03; Mar. 2006.

U.S. Appl. No. 29/358,468, filed Mar. 26, 2010.

U.S. Appl. No. 29/358,472, filed Mar. 26, 2010.

U.S. Appl. No. 29/384,169, filed Jan. 27, 2011.

L1 Package; 2008; pp. 1-3.

* cited by examiner

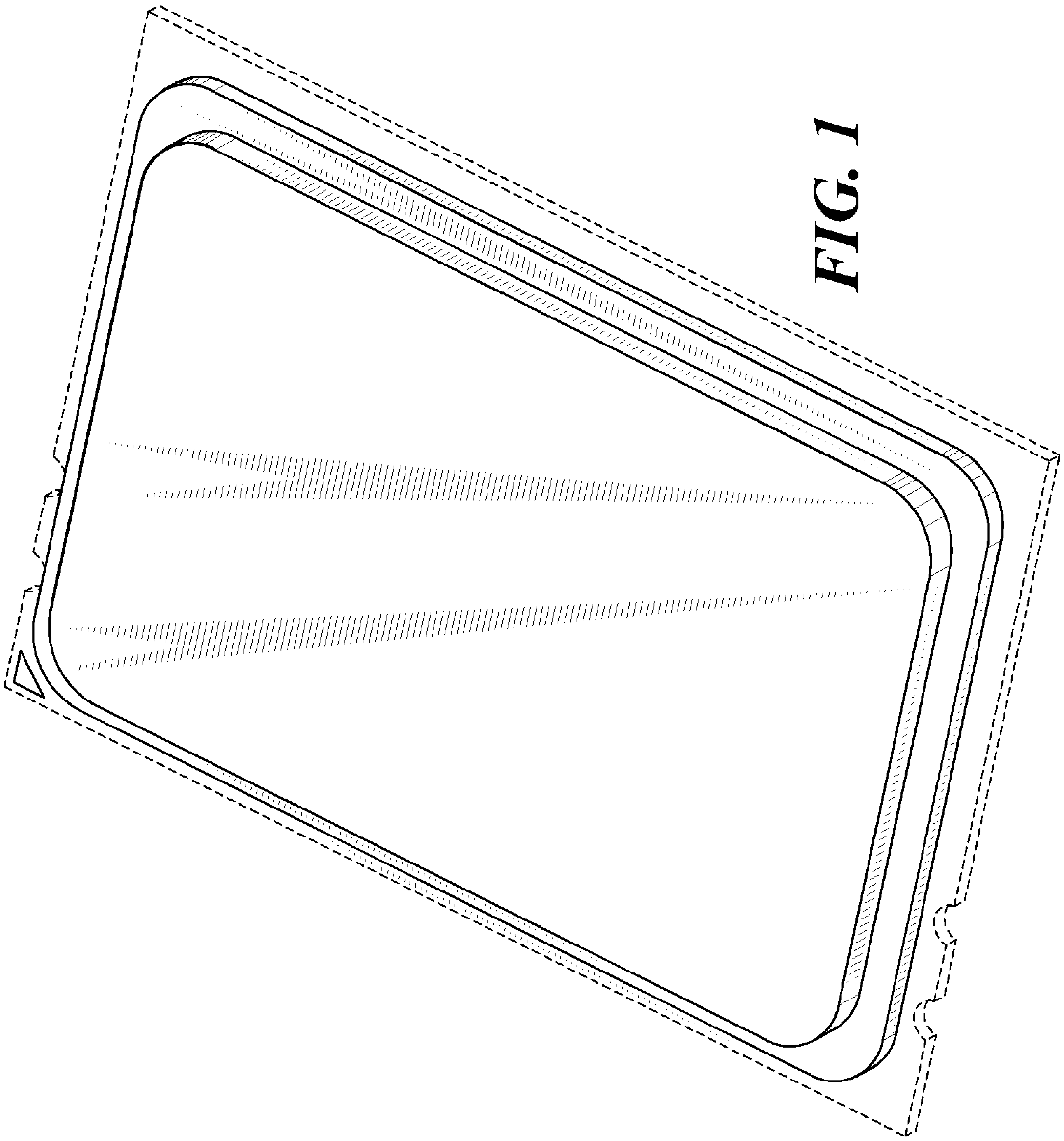


FIG. 1

FIG. 2

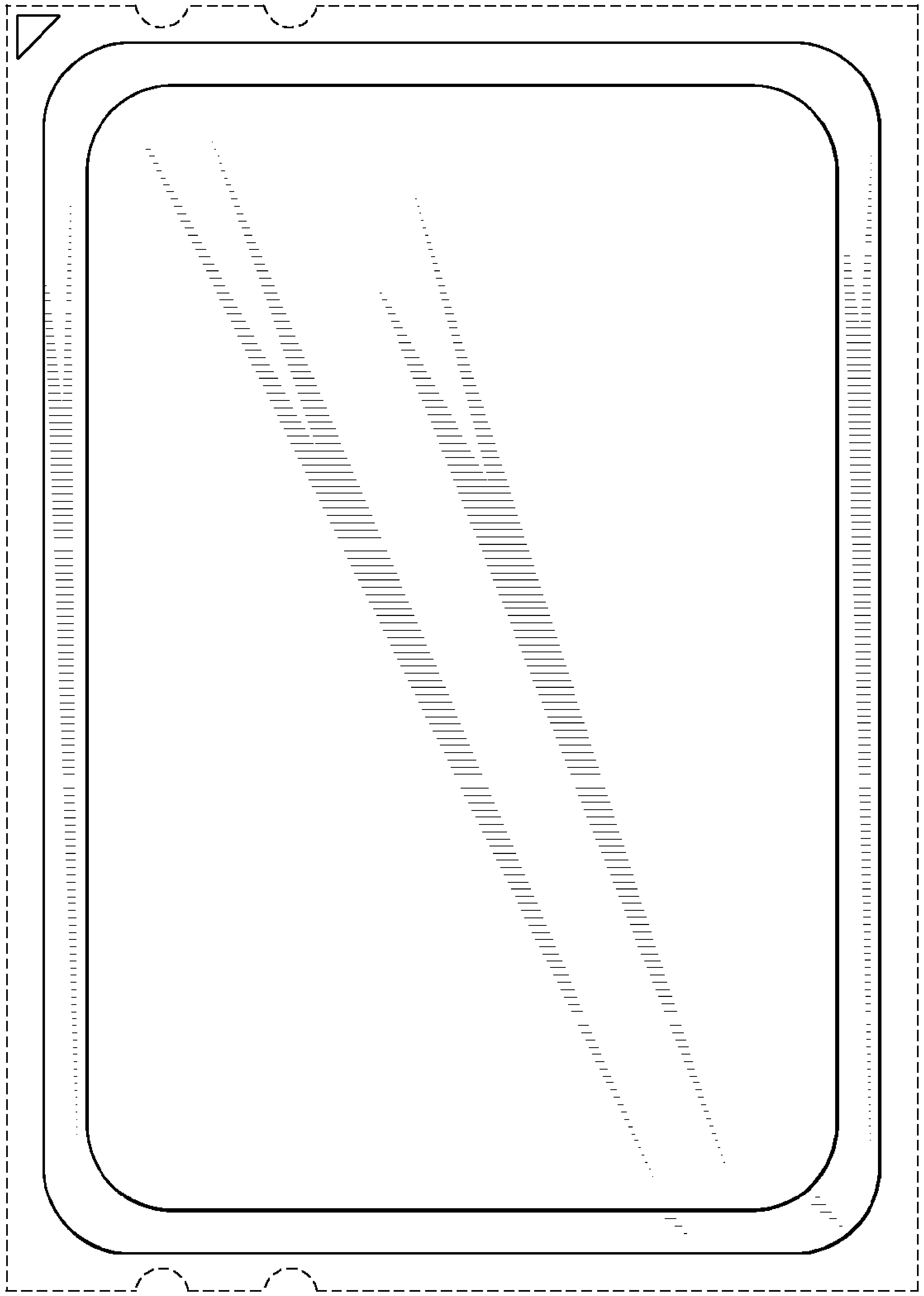


FIG. 3

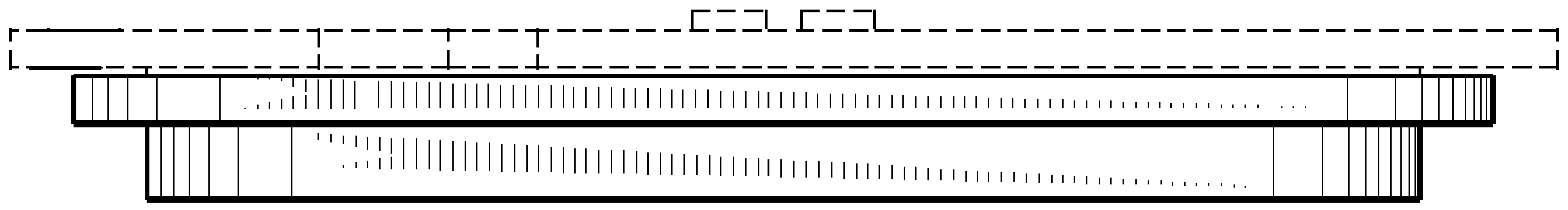


FIG. 4

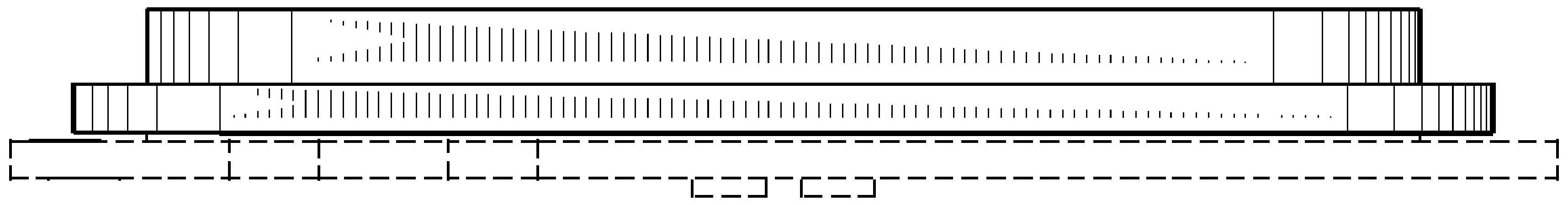


FIG. 5

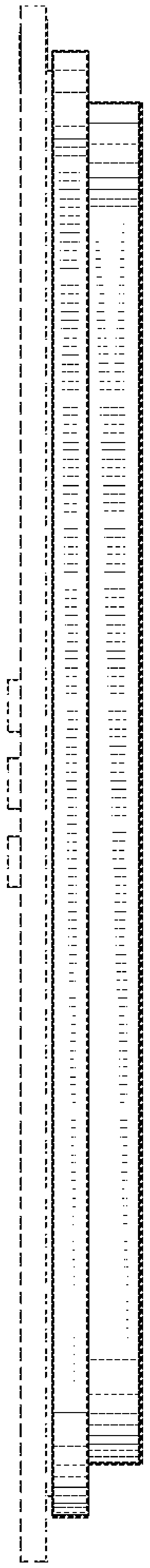


FIG. 6

FIG. 7